

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1360	257/777.ccls.	USPAT	OR	ON	2007/02/12 23:19
L2	7	1 and ((IC (integrated adj circuit) component die chip) with driver with impedance)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/12 23:20
L3	7	2 and (substrate PCB board) and package	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/02/12 23:19
L4	459	257/777.ccls.	US-PGPUB	OR	ON	2007/02/12 23:19
L5	0	4 and ((IC (integrated adj circuit) component die chip) with driver with impedance)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/12 23:20
S1	1603	(IC (integrated adj circuit) component die chip) with driver with impedance	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/12 20:27
S2	311	S1 and (substrate PCB board) and package	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/02/12 20:28
S3	195	S2 and (interposer spacer interconnect\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/02/10 03:20
S4	148	@ad:<="20031031" and S3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/02/12 20:28

EAST Search History

S5	1603	(IC (integrated adj circuit) component die chip) with driver with impedance	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/10 15:34
S6	311	S5 and (substrate PCB board) and package	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/02/12 23:19
S7	195	S6 and (interposer spacer interconnect\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/02/10 15:34
S8	148	@ad <= "20031031" and S7	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/02/12 20:25
S9	7608	257/723-724.ccls. or 257/678.ccls. or 257/686.ccls. or 257/737-738.ccls. or 257/774.ccls.	USPAT	OR	ON	2007/02/12 20:32
S10	14	S9 and ((IC (integrated adj circuit) component die chip) with driver with impedance)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/12 23:19
S11	12	S10 and (substrate PCB board) and package	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/02/12 20:43
S12	10	@ad <= "20031031" and S11	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/02/12 20:32
S13	2750	438/109.ccls. or 438/106-107.ccls.	USPAT	OR	ON	2007/02/12 20:33

EAST Search History

S14	3	S13 and ((IC (integrated adj circuit) component die chip) with driver with impedance)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/12 20:32
S15	3	S14 and (substrate PCB board) and package	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/02/12 20:32
S16	3	@ad <= "20031031" and S15	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/02/12 20:33
S17	4160	257/723-724.ccls. or 257/678.ccls. or 257/686.ccls. or 257/737-738.ccls. or 257/774.ccls.	US-PGPUB	OR	ON	2007/02/12 20:32
S18	4	S17 and ((IC (integrated adj circuit) component die chip) with driver with impedance)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/12 20:32
S19	3	S18 and (substrate PCB board) and package	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/02/12 20:33
S20	1	@ad <= "20031031" and S19	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/02/12 20:43
S21	1668	438/109.ccls. or 438/106-107.ccls.	US-PGPUB	OR	ON	2007/02/12 20:33
S22	1	S21 and ((IC (integrated adj circuit) component die chip) with driver with impedance)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/12 23:19

EAST Search History

S23	3093	361/803-804.ccls. or 361/784-785.ccls. or 361/780.ccls. or 361/794.ccls. or 361/790.ccls. or 361/749.ccls. or 361/751.ccls. or 361/789.ccls.	USPAT	OR	ON	2007/02/12 20:40
S24	6	S23 and ((IC (integrated adj circuit) component die chip) with driver with impedance)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/12 20:38
S25	3	S24 and (substrate PCB board) and package	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/12 20:38
S26	398	361/803-804.ccls. or 361/784-785.ccls. or 361/780.ccls. or 361/794.ccls. or 361/790.ccls. or 361/749.ccls. or 361/751.ccls. or 361/789.ccls.	US-PGPUB	OR	ON	2007/02/12 20:40
S27	0	S26 and ((IC (integrated adj circuit) component die chip) with driver with impedance)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/12 20:42
S28	1295	361/761.ccls. or 361/764.ccls. or 361/766.ccls. or 361/782.ccls.	USPAT	OR	ON	2007/02/12 20:43
S29	7	S28 and ((IC (integrated adj circuit) component die chip) with driver with impedance)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/12 20:45
S30	4	S29 and (substrate PCB board) and package	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/02/12 20:43
S31	3	@ad <= "20031031" and S30	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/02/12 20:44